

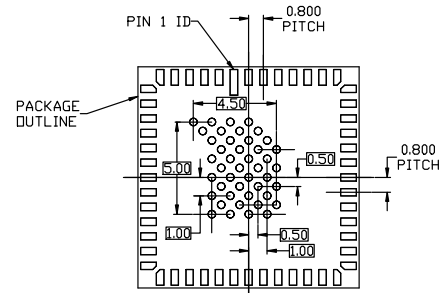
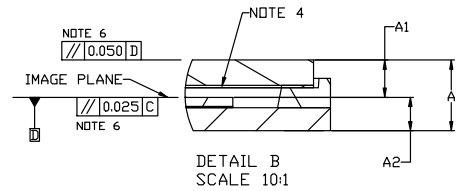
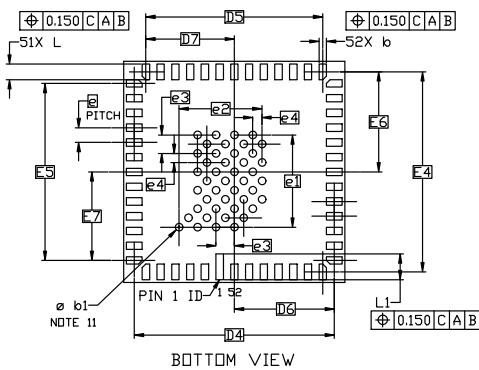
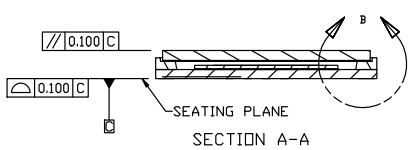
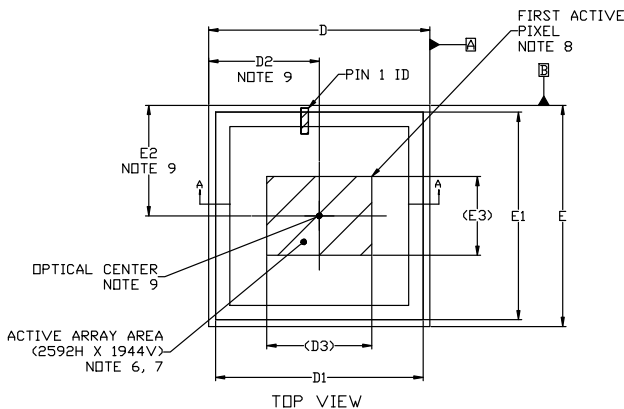
mPLCC52 12.00x12.00x1.53, 0.80P  
CASE 776AW  
ISSUE E

DATE 18 OCT 2023

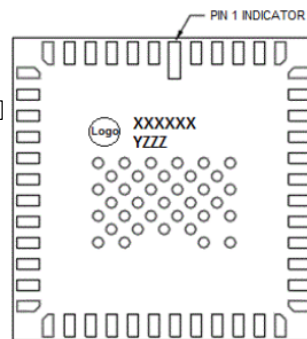
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. GLASS: 0.550 THICKNESS; REFRACTIVE INDEX = 1.52.
4. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.260 THICKNESS.
5. COPLANARITY APPLIES TO THE PLATED LAND PADS.
6. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
7. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B  $\pm 0.5^\circ$ .
8. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
9. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.000, 0.000).
10. PACKAGE CENTER (X, Y) = (0.000, 0.000).
11. SOLDER MASK OPENINGS FOR THERMAL CONNECTION PADS.

MILLIMETERS				MILLIMETERS			
DIM	MIN	NDM	MAX	DIM	MIN	NDM	MAX
A	1.435	1.535	1.635	E1	11.210	11.260	11.310
A1	0.710	0.810	0.910	E2	5.900	6.000	6.100
A2	0.650	0.725	0.800	E3	4.276 (REF)		
b	0.350	0.400	0.450	E4	10.850 BSC		
b1	0.350	0.400	0.450	E5	9.600 BSC		
D	11.900	12.000	12.100	E6	5.425 BSC		
D1	11.210	11.260	11.310	E7	4.800 BSC		
D2	5.900	6.000	6.100	e	0.800 BSC		
D3	5.702 (REF)			e1	5.000 BSC		
D4	10.850 BSC			e2	4.500 BSC		
D5	9.600 BSC			e3	1.000 BSC		
D6	5.425 BSC			e4	0.500 BSC		
D7	4.800 BSC			L	0.800	0.850	0.900
E	11.900	12.000	12.100	L1	1.350	1.400	1.450



GENERIC MARKING DIAGRAM\*



RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SILDERRM/D.

XXXX = Specific Device Code  
Y = Year  
ZZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	mPLCC52 12.00x12.00x1.53, 0.80P	PAGE 1 OF 1

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